

Chip Bead For EMI Suppression

CIS10P Series (1608/ EIA 0603)

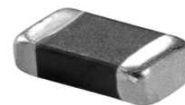
APPLICATION

Noise Suppression in power line

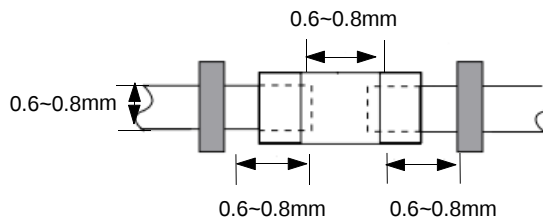
FEATURES

Smallest beads used in high current.

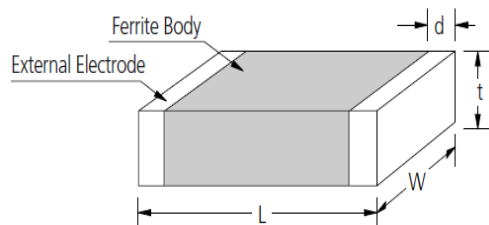
- CIS series is used for high current. (~ 6A)



RECOMMENDED LAND PATTERN



DIMENSION



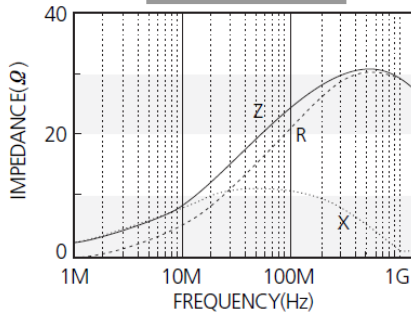
Type	Dimension [mm]			
	L	W	t	d
10	1.6 ±0.15	0.8 ±0.15	0.6±0.15, 0.8±0.15	0.3 ±0.2

DESCRIPTION

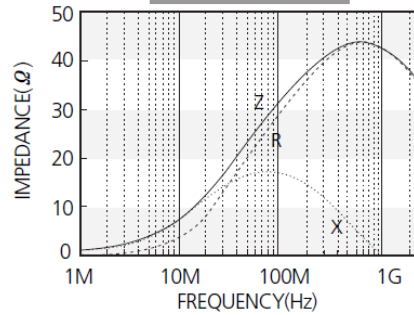
Part No.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIS10P260AC	0.6±0.15	26	0.007	6000
CIS10P300AC	0.6±0.15	30	0.01	6000
CIS10P700AC	0.6±0.15	70	0.02	4000
CIS10P101AC	0.6±0.15	100	0.03	3000
CIS10P121AC	0.6±0.15	120	0.03	3000
CIS10P181AC	0.6±0.15	180	0.04	2500
CIS10P221NC	0.8±0.15	220	0.05	2500
CIS10P301NC	0.8±0.15	300	0.07	2000
CIS10P331NC	0.8±0.15	330	0.07	1700
CIS10P391NC	0.8±0.15	390	0.10	1200
CIS10P471NC	0.8±0.15	470	0.13	1500
CIS10P601NC	0.8±0.15	600	0.15	1300

CHARACTERISTIC DATA

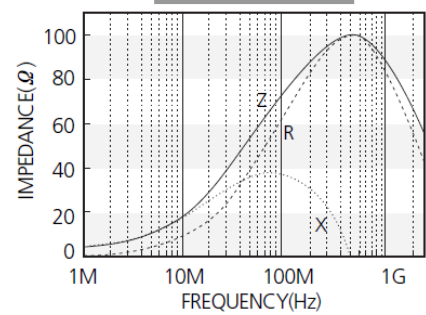
CIS10P260



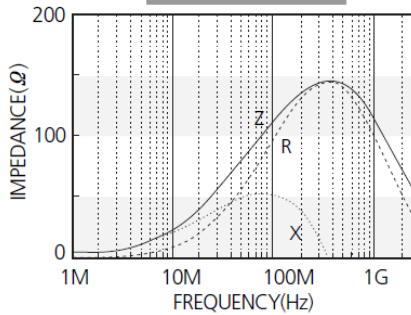
CIS10P300



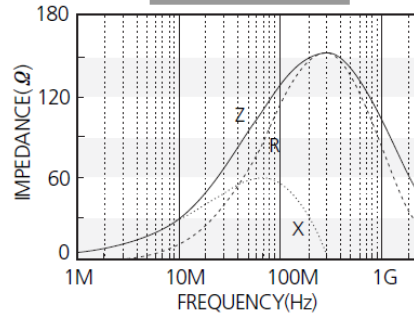
CIS10P700



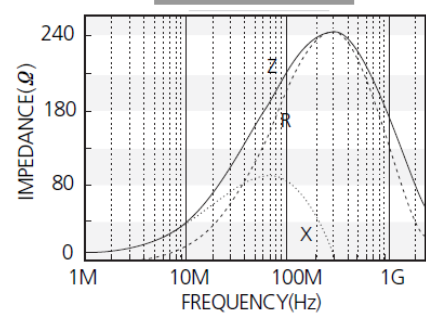
CIS10P101



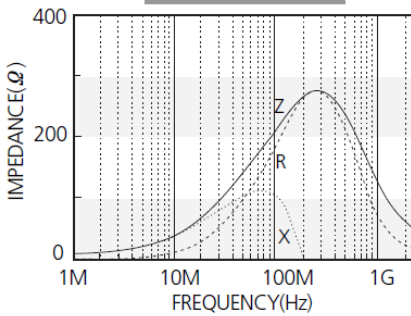
CIS10P121



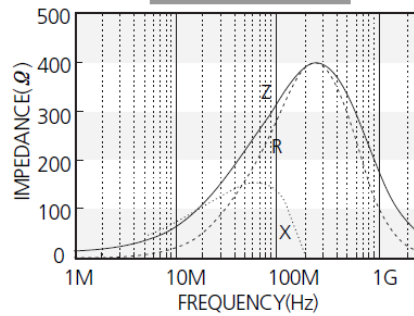
CIS10P181



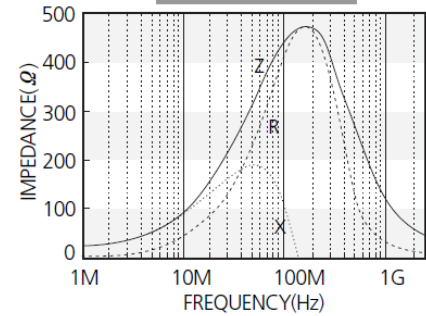
CIS10P221



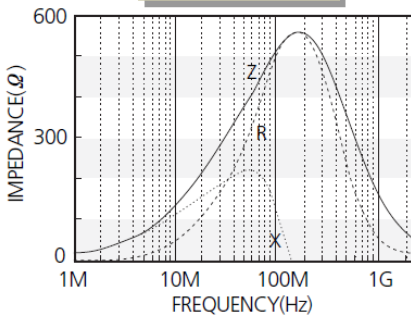
CIS10P331



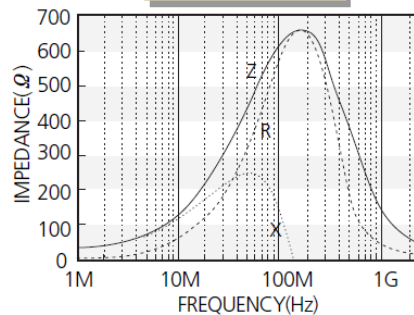
CIS10P391



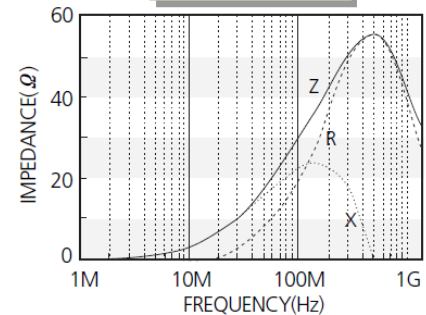
CIS10P471



CIS10P601



CIS10J300



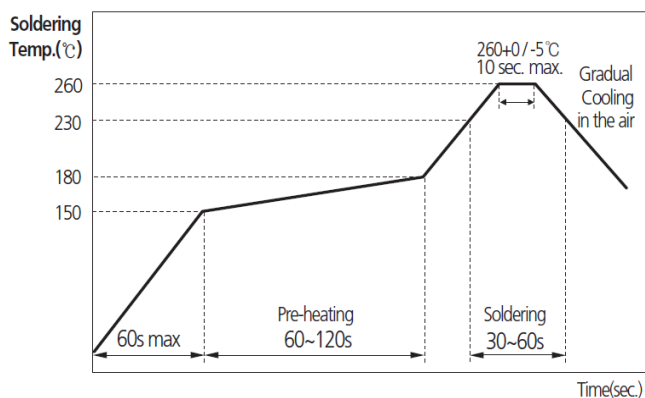
PRODUCT IDENTIFICATION

CI	S	10	P	300	A	C
(1)	(2)	(3)	(4)	(5)	(6)	(7)

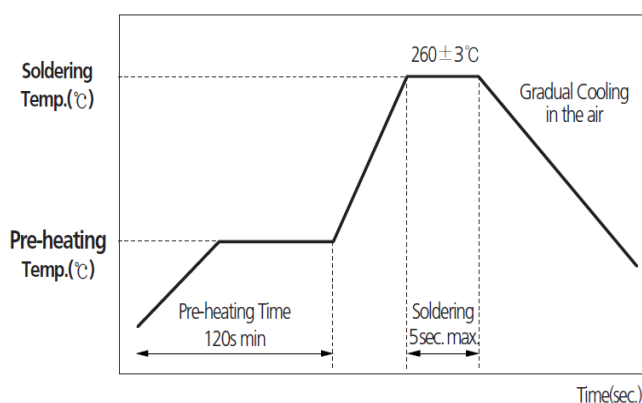
- | | |
|--|------------------------------|
| (1) Chip Beads | (2) Ultra high current (~6A) |
| (3) Dimension | (4) Material Code |
| (5) Nominal impedance (300:30Ω, 121:120Ω) | |
| (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard) | |
| (7) Packaging(C:paper tape, E:embossed tape) | |

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4000